

REMARKS/ARGUMENTS

Favorable reconsideration of this application is respectfully requested in view of the following remarks.

Claims 14 -26 are currently active in this case. Applicants note that the outstanding Official Action is directed to claims 1-13. Those claims were cancelled and replaced by claims 14-26 by the February 14, 2005 preliminary amendment. As stated in the Remarks of the preliminary amendment, claims 14-26 are not believed to be more narrow in scope in any aspect in comparison with cancelled claims 1-13.

In the outstanding Office Action, claims 1-6 and 13 were rejected under 35 USC 102(b) as being anticipated by U.S. Patent No. 6,525,275 to Asai; and claims 7-12 were rejected under 35 USC 103(a) as being unpatentable over Asai.

The present invention is directed to a process for forming bumps on electrode pads for a wiring board including a substrate and a plurality of the electrode pads. The process includes the steps of forming a laminated two-layer film on the wiring board and forming a pattern of apertures at positions corresponding to the electrode pads forming the bumps; and peeling and removing the laminated two-layer film from the wiring board. In view of the peeling and removing step, it is clear that the laminated two-layer film of the invention is not a permanent film. By using the removable laminated two-layer film, a reduction of solder bump pitch can be achieved.

In contrast thereto, the layer 5 of Asai is an interlaminar insulating layer and thus is a permanent layer which cannot be peeled or removed. See column 7, line 57 of Asai. Further, the layer 6 of Asai if formed on the layer 5 and subsequently the layer 10 is formed on the layer 6. See column 11 lines 3-59 in Fig. 1A. Thus, the layer 6 is also a permanent layer that cannot be peeled or removed. Consequently, Asai's layer 5 and layer 6 do not anticipate or suggest the lower layer and upper layer of the two-layer film defined by claim 14. In fact,

Applicants respectfully submit that the layer 5 and the layer 6 of Asai function more like the solder resist shown in Fig. 5A of the present specification.

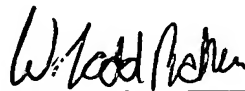
Regarding the Fig. 8A of Asai relied upon in the Office Action, Applicants point out that that figure is a view illustrating the shape of a solder bump of the case where no solder resist is used. That is, Fig. 8A is not a view illustrating the state of a solder bump after peeling and removing a laminated two-layer film from the board as defined by the present invention. Therefore, Fig. 8A of Asai does not teach or suggest step D of claim 14. In view of the foregoing, Asai is not believed to anticipate or render obvious the subject matter recited by claim 14.

Applicants respectfully traverse the rejection of claims 7-12 as being obvious over the Asai patent. Applicants traverse the rejection on the ground that a *prima facie* case of obviousness has not been made. Rather, a broad assertion had been made that each of the features recited by the dependent claim was well known. Further, for the reasons discussed above, the Asai patent fails to teach at least the peeling and removing step of independent claim 14. Consequently, claims 15-26 are believed to be allowable for at least the same reasons that claim 14 is believed to be allowable.

In view of the foregoing remarks, no further issues are believed to be remaining. An early and favorable action is therefore respectfully requested.

Respectfully submitted,

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